



US00D465462S

(12) **United States Design Patent**  
**Hsieh**

(10) **Patent No.:** **US D465,462 S**

(45) **Date of Patent:** **\*\* Nov. 12, 2002**

(54) **BASE FOR A HEAT DISSIPATING ASSEMBLY**

(76) **Inventor:** **Hsin-Mao Hsieh**, No. 6, East Section, Chiao Nan Li, Industrial 6th Rd., Pingtung City, Pingtung Hsien (TW)

(\*\*) **Term:** **14 Years**

(21) **Appl. No.:** **29/145,500**

(22) **Filed:** **Jul. 24, 2001**

(51) **LOC (7) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/179**

(58) **Field of Search** ..... D13/179; 174/16.3; 257/706, 707, 718, 719, 720, 721, 722, 727, 686; 361/271, 274.3, 697, 702, 704, 709, 710, 711

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

- D315,832 S \* 4/1991 Rocheleau et al. .... D13/179
- 5,368,094 A \* 11/1994 Hung ..... 165/80.3
- D357,670 S \* 4/1995 Dodson ..... D13/179
- 5,495,392 A \* 2/1996 Shen ..... 361/697

- 6,161,611 A \* 12/2000 Cheng ..... 165/80.3
- 6,246,584 B1 \* 6/2001 Lee et al. .... 361/704
- D450,044 S \* 11/2001 Lindstrom ..... D13/179
- 6,373,701 B1 \* 4/2002 Lo ..... 361/704

\* cited by examiner

*Primary Examiner*—Ted Shooman

*Assistant Examiner*—Selina Sikder

(74) *Attorney, Agent, or Firm*—Thorp Reed & Armstrong LLP

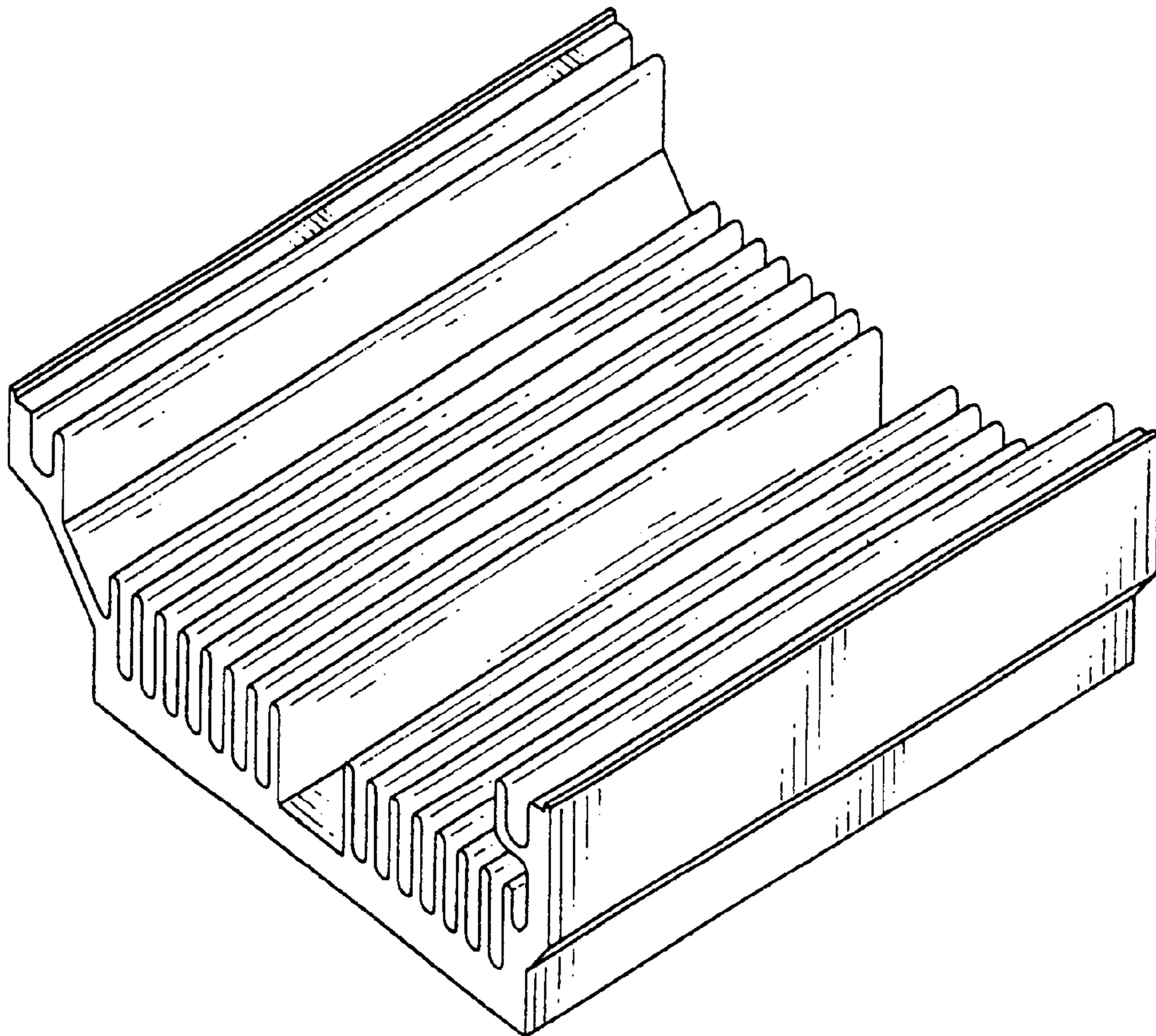
(57) **CLAIM**

The ornamental design for a base for a heat dissipating assembly, as shown.

**DESCRIPTION**

FIG. 1 is a perspective view of a base for a heat dissipating assembly, showing my new design;  
 FIG. 2 is a front elevational view thereof;  
 FIG. 3 is a rear elevational view thereof;  
 FIG. 4 is a left side elevational view thereof;  
 FIG. 5 is a right side elevational view thereof;  
 FIG. 6 is a top plan view thereof; and,  
 FIG. 7 is a bottom plan view thereof.

**1 Claim, 4 Drawing Sheets**



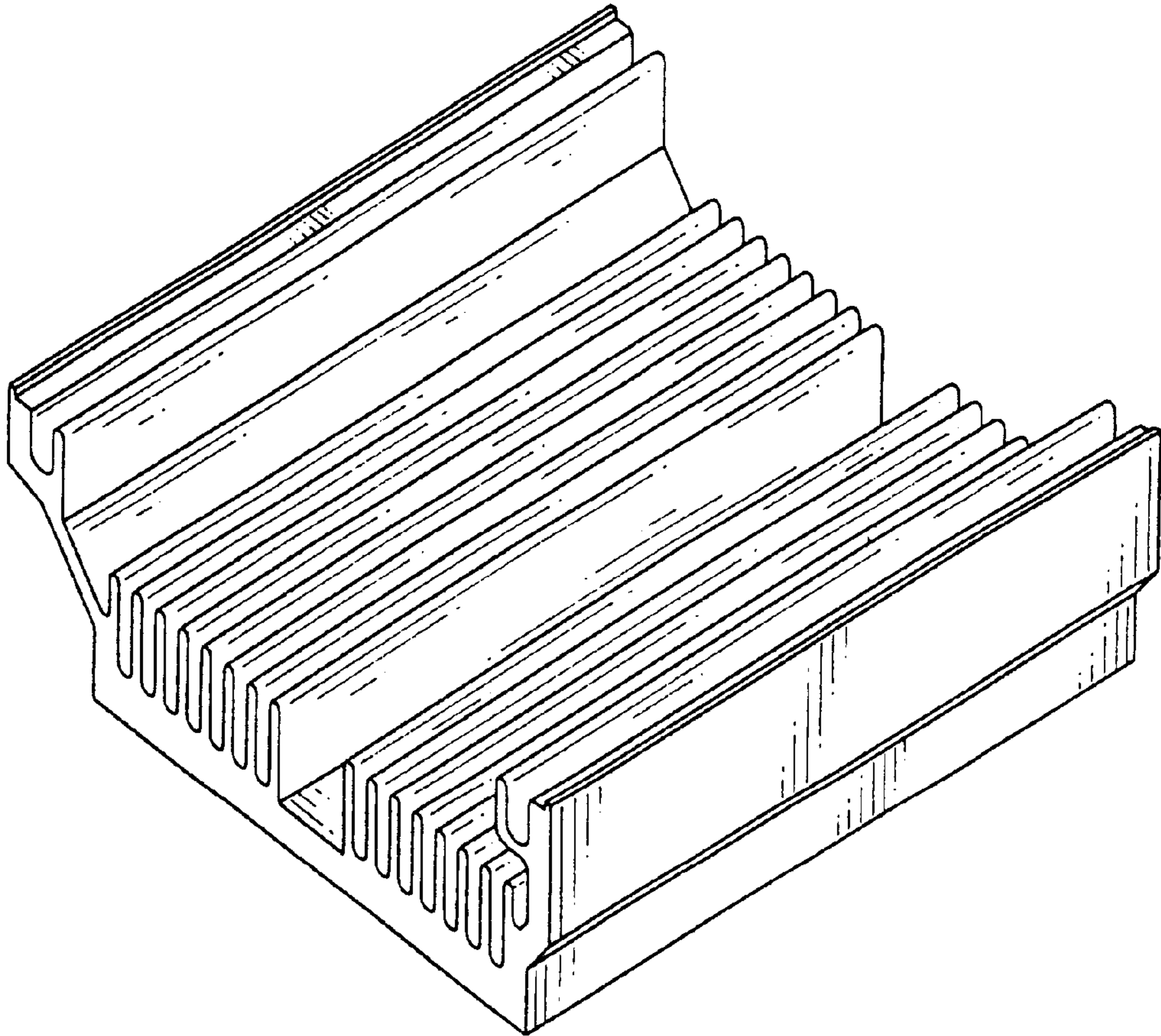


FIG. 1

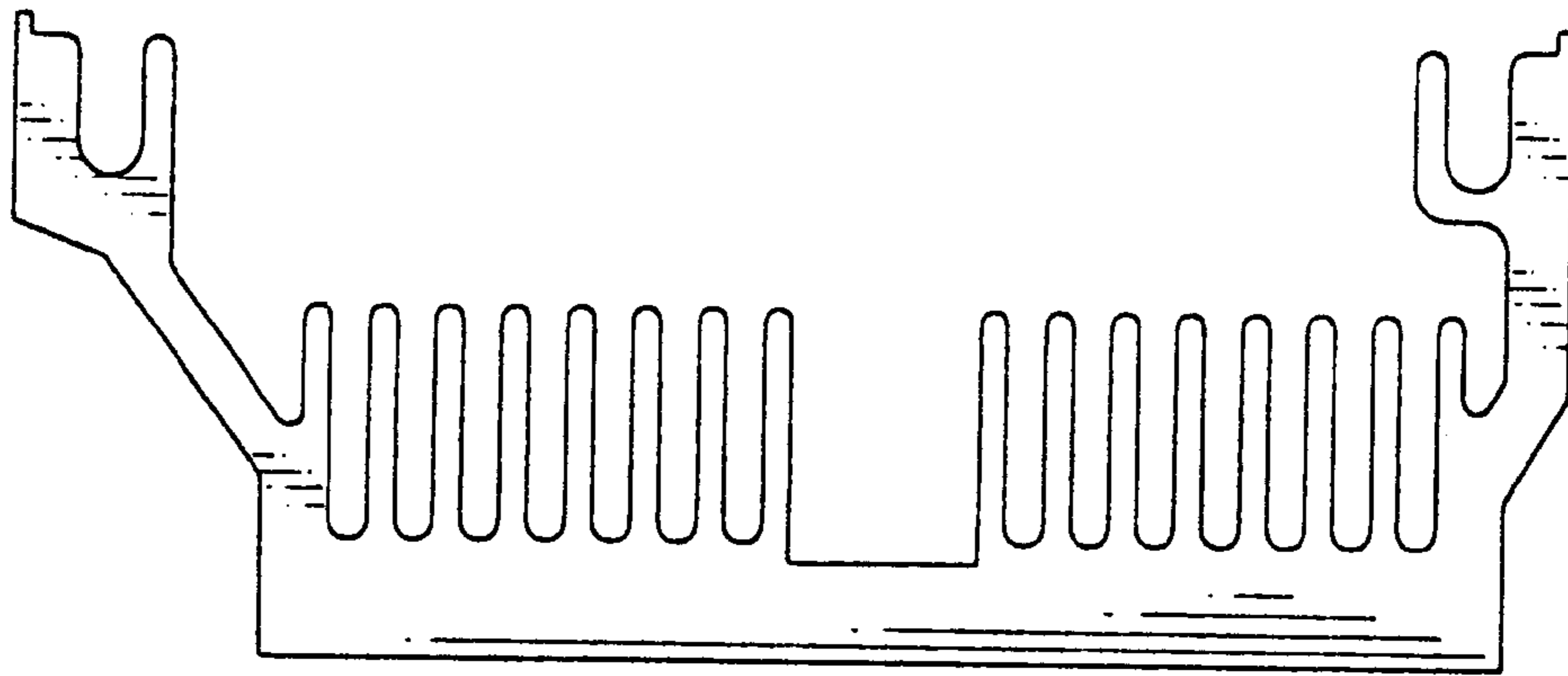


FIG. 2

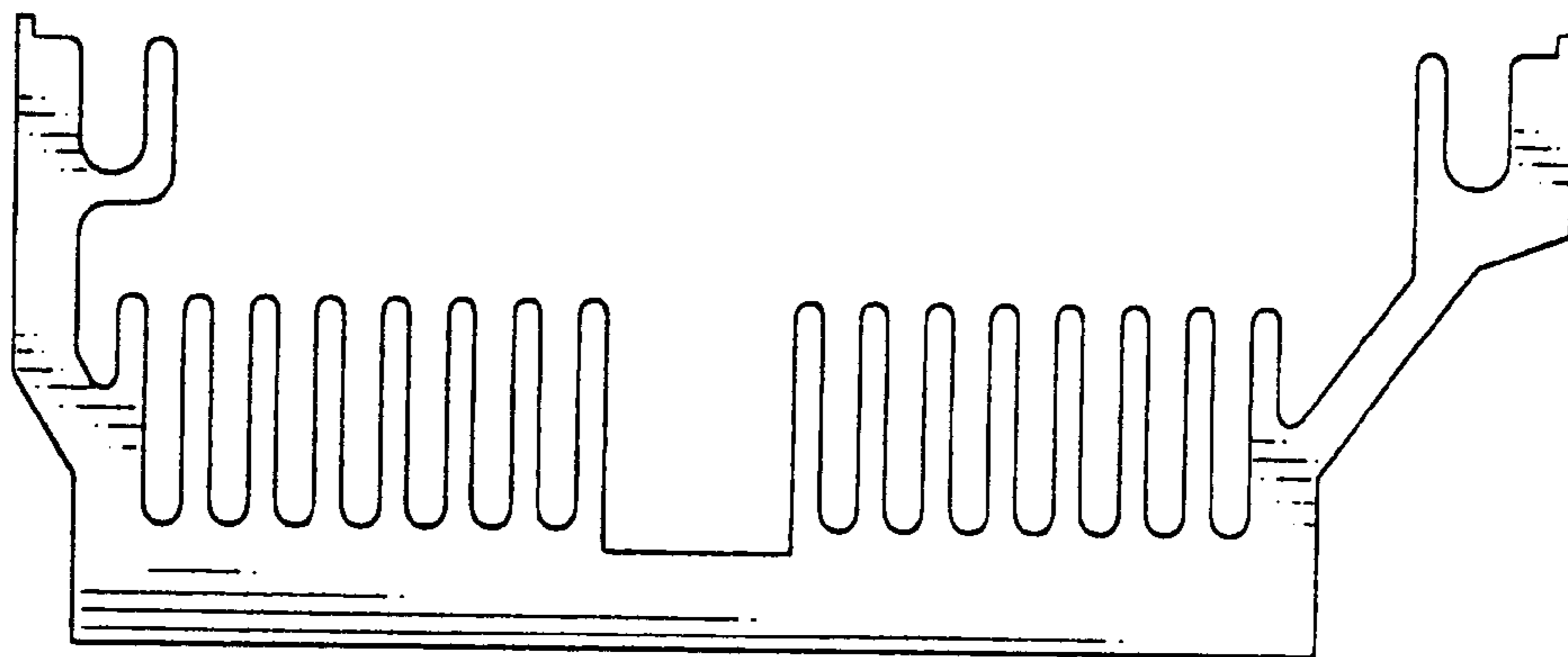


FIG. 3

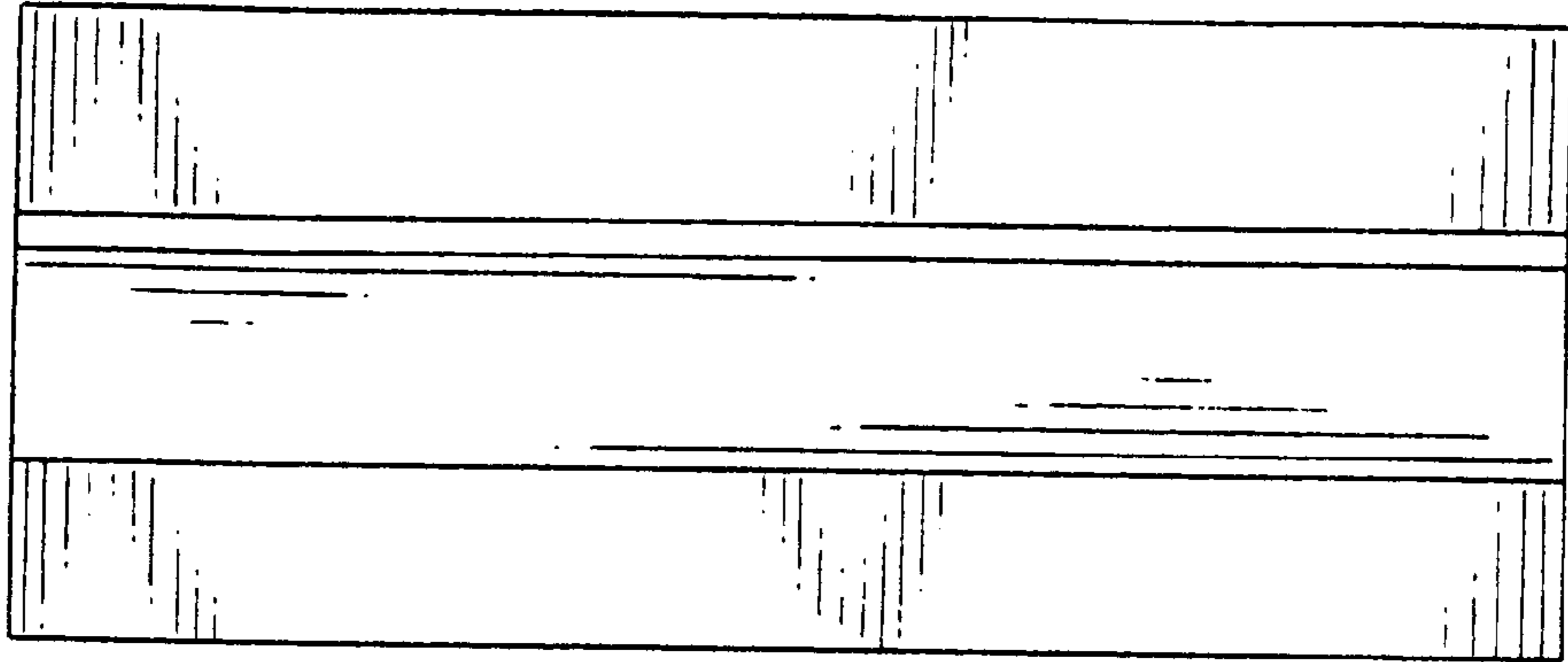


FIG. 4

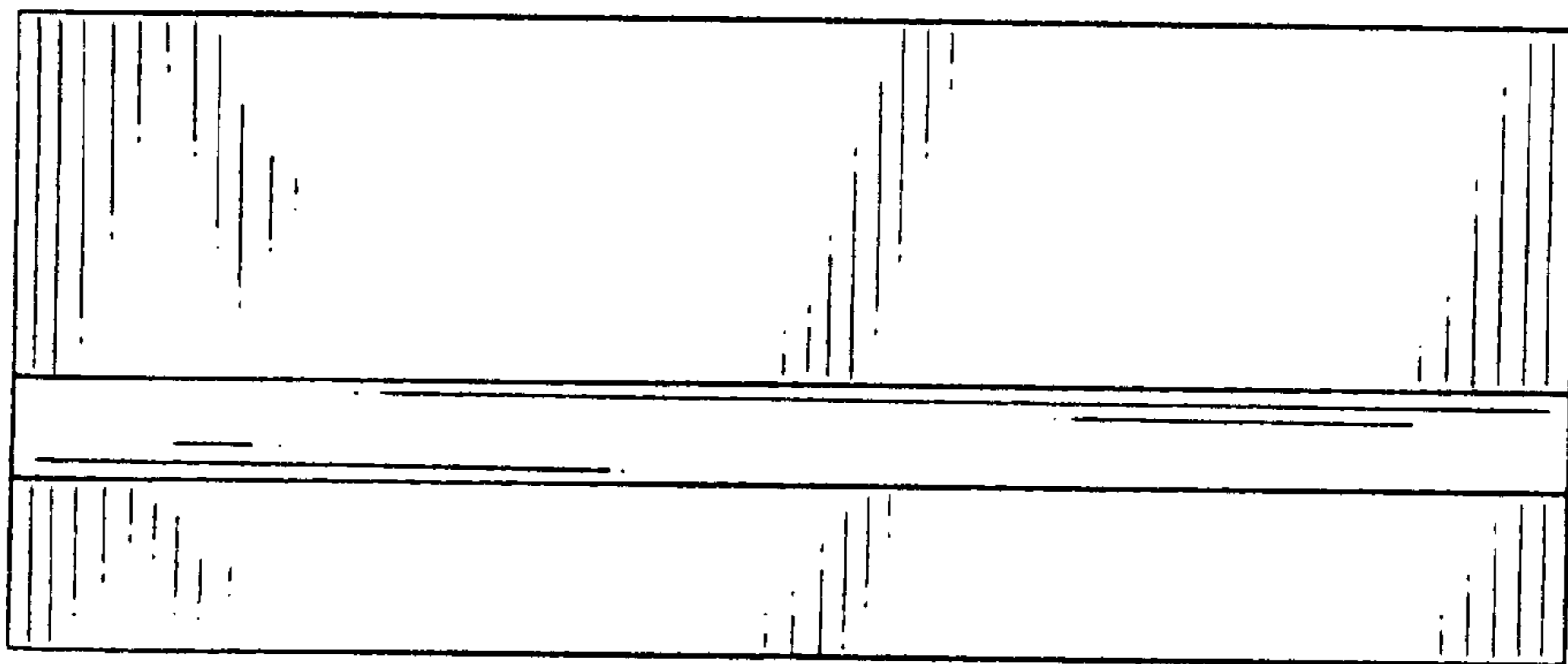


FIG. 5

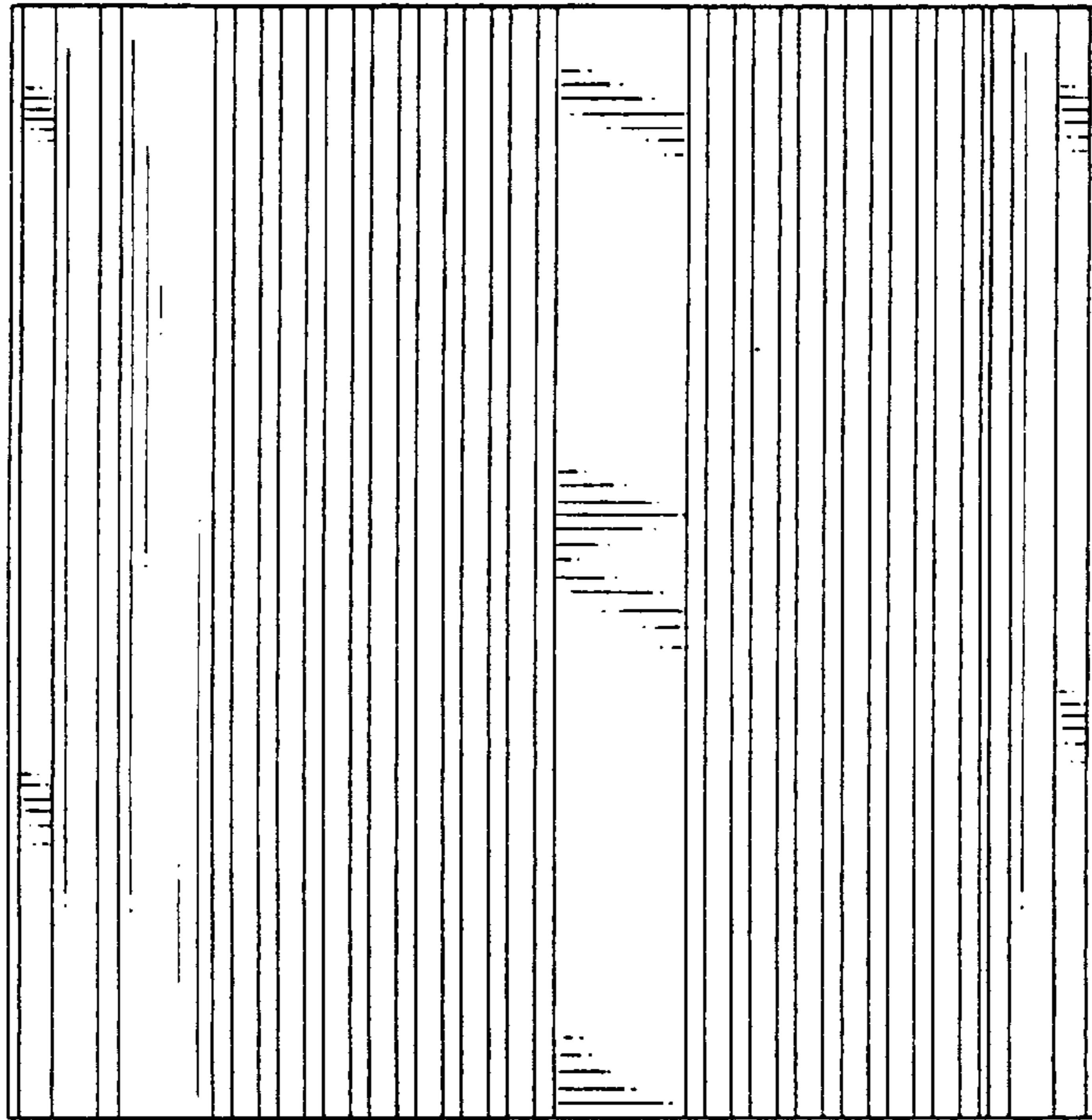


FIG. 6

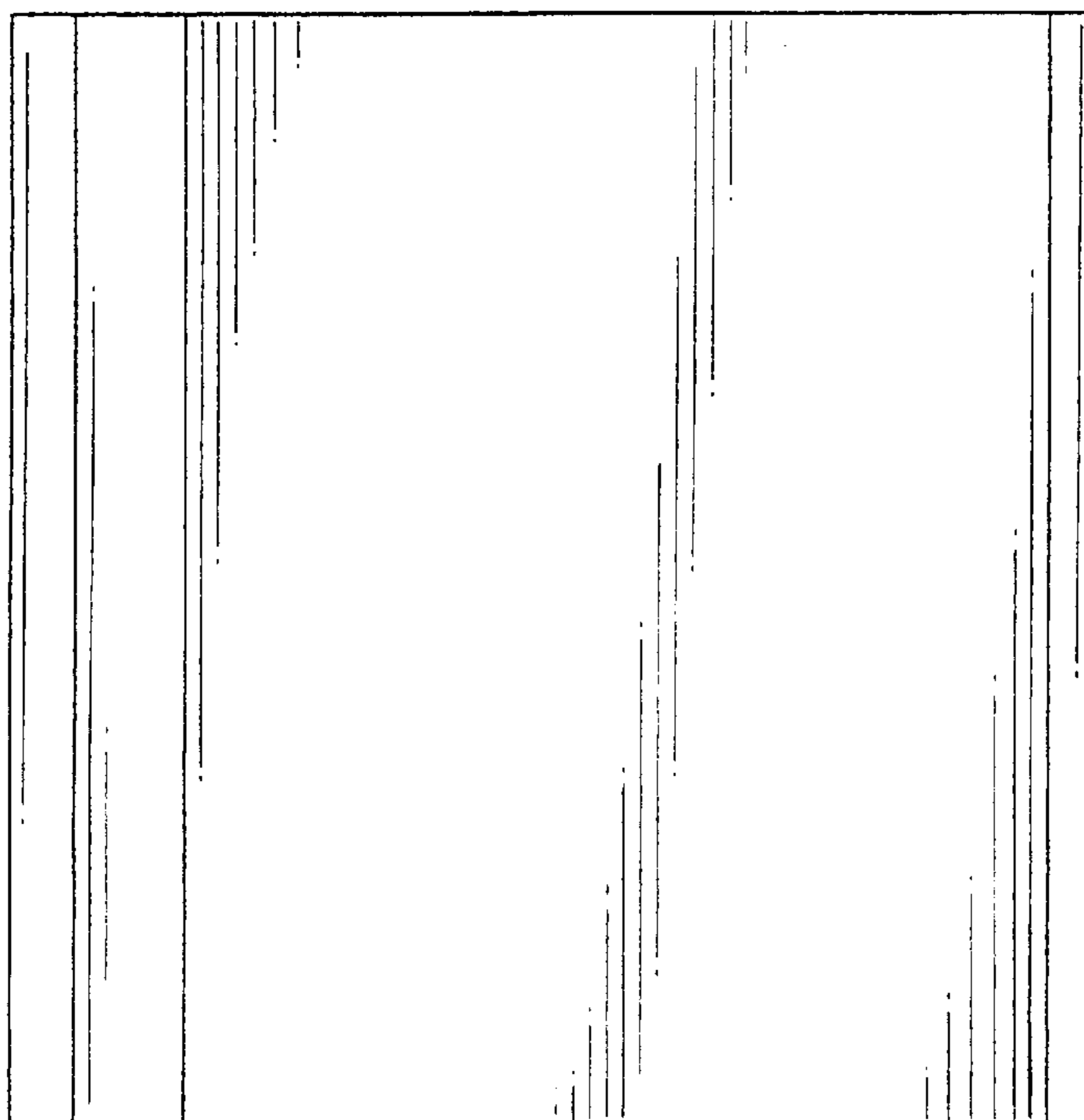


FIG. 7